产品承认书
SPECIFICATION FOR APPROVAL

CUSTOMER:

CUSTOMER P/N:

CD.com P/N. : T0412D

DESCRIPTION: Common Mode Choke

REF NO:

REV/NO: A/2

DATE: 2021-3-31

ATTACHMENT:

- ■ **SPECIFICATION**
- ■ **SAMPLE** **Q'TY OF SAMPLES ______ PCS**

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			

JXD

深圳磁联达电子有限公司

Shenzhen magnetic Lianda Electronics Co. Ltd.

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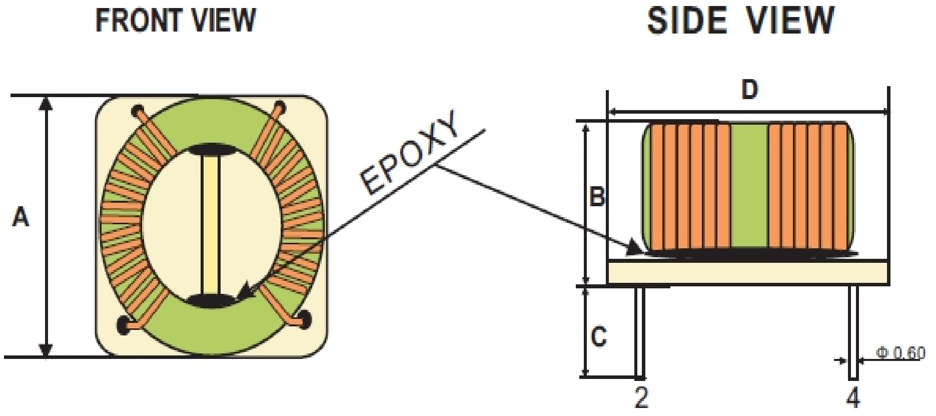
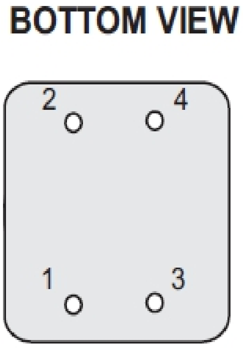
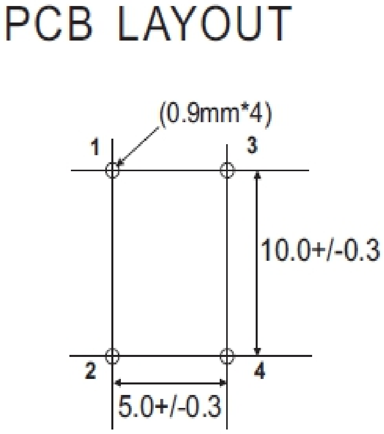
RoHS Compliant
Pb

1. DIMENSIONS & MARKING:



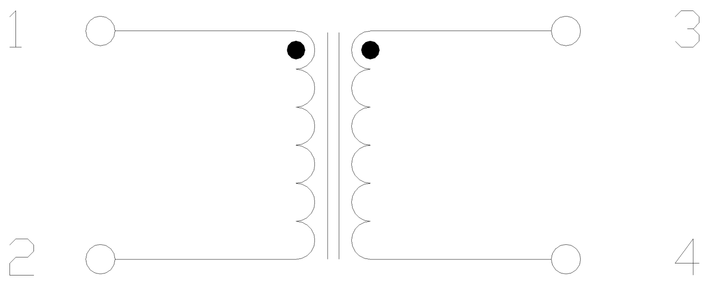




Unit: mm

A MAX.	B MAX.	C +/-0.5	D Max
16.5	11.0	4.0	16.5

2. SCHEMATICS:



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3. WINDING SPEC:

端子Terminal	线规 Wire Gauge	圈数 Turns	备注 Remark
1-2	2UEW 0.60mm 180℃	25Ts	
3-4	2UEW 0.60mm 180℃	25Ts	

4.ELECTRICAL SPECIFICATIONS @25℃

4.1 Inductance：(1-2) = (3-4) = 8mH MIN @ 1KHz 0.25V;
4.2 Turns Ratio：(1-2) : (3-4) = 1:1±1% @10KHz, 0.1Vac;
4.3 DCR：(1-2) = 0.60Ω MAX (3-4) = 0.60Ω MAX;
4.4 ΔL：L(1-2)-L(3-4) @1KHz, 1V ≤ 1%
4.5 Rated Current：ΔT≤45℃ 4.5A
4.6 Hi-Pot：1mA/2S/60Hz (Vac) : (1-2) TO (3-4) 600V
4.7 Insulation Resistance：DC100V ≥100MΩ MIN.

5.MATERIALLIST

Item	Material	Partnumber/supplier	UL file
Core	T13*8*6 Hg103	ENCORE	
Copper wire	2UEW 0.60mm 180℃	SHING SHUN	
Base	FR4		
Stannum	Sn99.3-Cu0.7	YUNXI	
Epoxy	3300A/3300B	EATTO	

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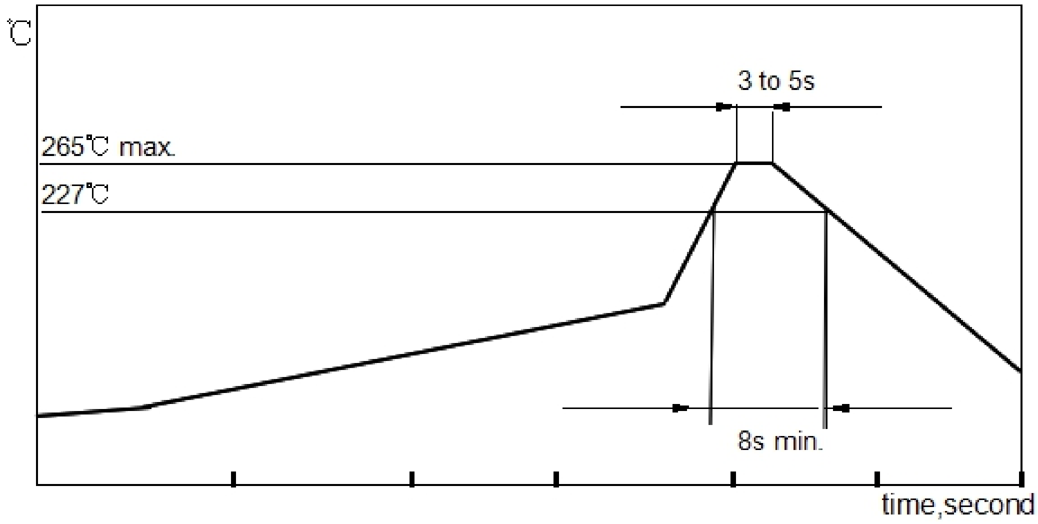
6. Recommended Lead Free IR Reflow Soldering Curve:



Item	Soldertechnique simulation	Temperature (℃)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder irno temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	10±1	25mm/s±6mm/s
3	Wave:TopsideBoard-mount product	260±5 (solder temp)	20±1	
4	Wave:BottomsideBoard-mount	260±5 (solder temp)	10±1	Preheat 1℃/s~4℃/s to within 100℃ of solder temp 25mm/s±6mm/s
5	Vapor phase reflow	215±5 (vapor temp)	215±5 (vapor temp)	

6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

6.2 Solderbility: Dipped in 245℃+/-5℃ molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

6.3 Resistance to soldering heat : Dip in 260℃+/- 5℃ molten solder for 5+/- 0.5 seconds. Shall not be any abnormality.

6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.

6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6.6 Dry heat: 100+/-2℃ 96 hours.

6.7 Cold: -20+/-2℃ 96 hours.

6.8 Damp Heat: 60+/-2℃, 93+/-3% RH 96 hours.

6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2℃,2-3minutes at 20+/-2℃,30 minutes at 85+/-2℃, 2-3 minutes at 20+/-2℃.

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